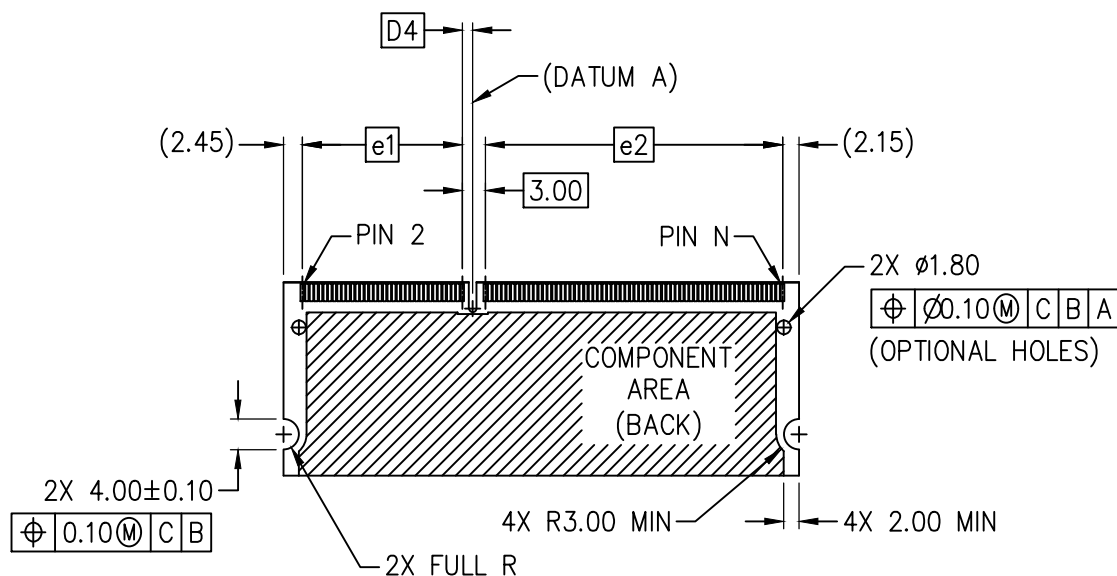
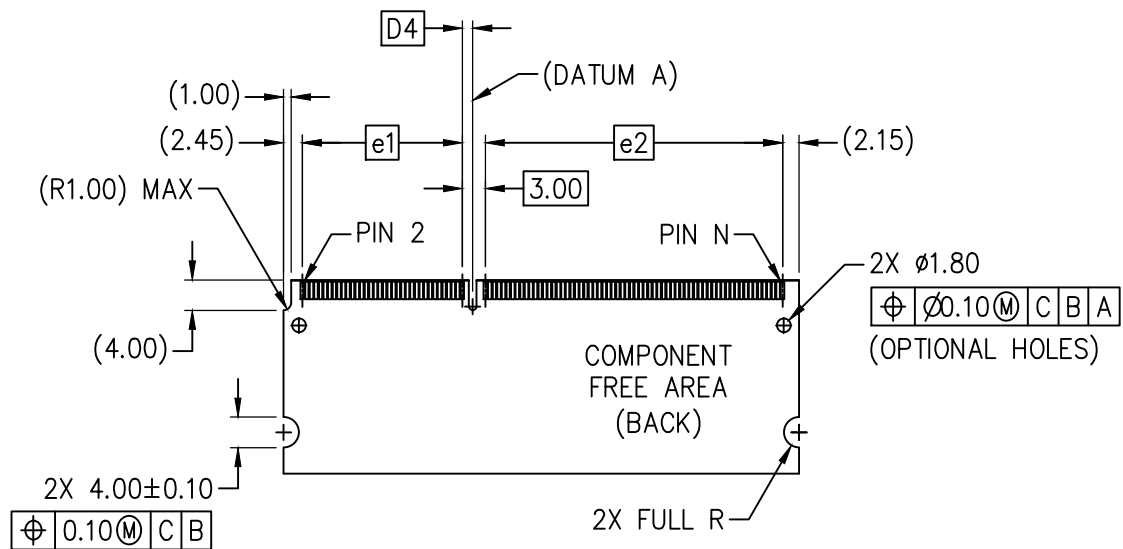
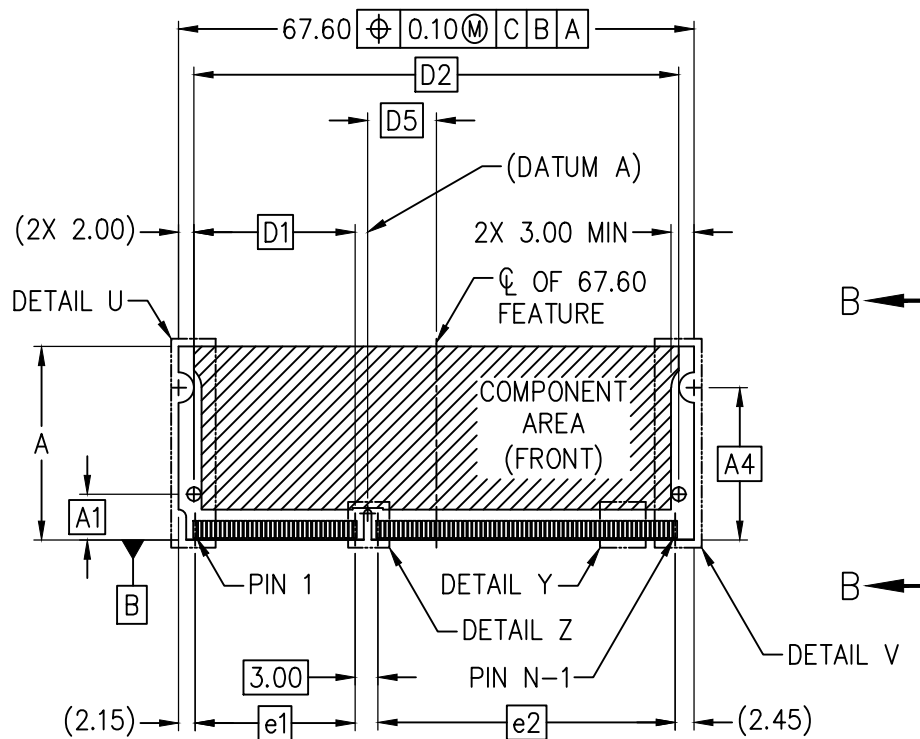
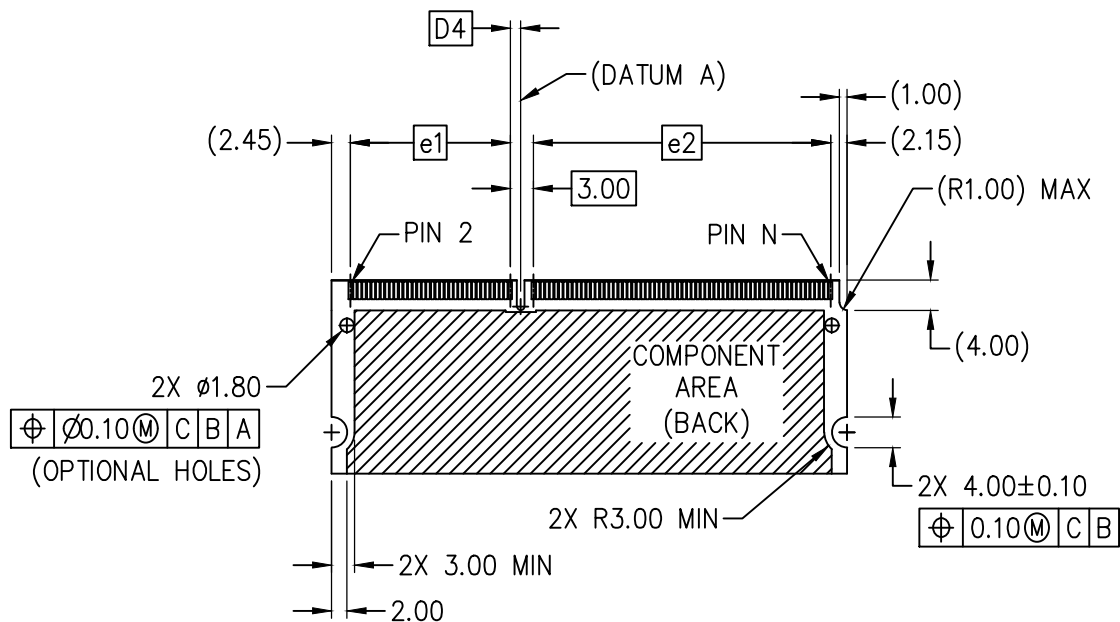
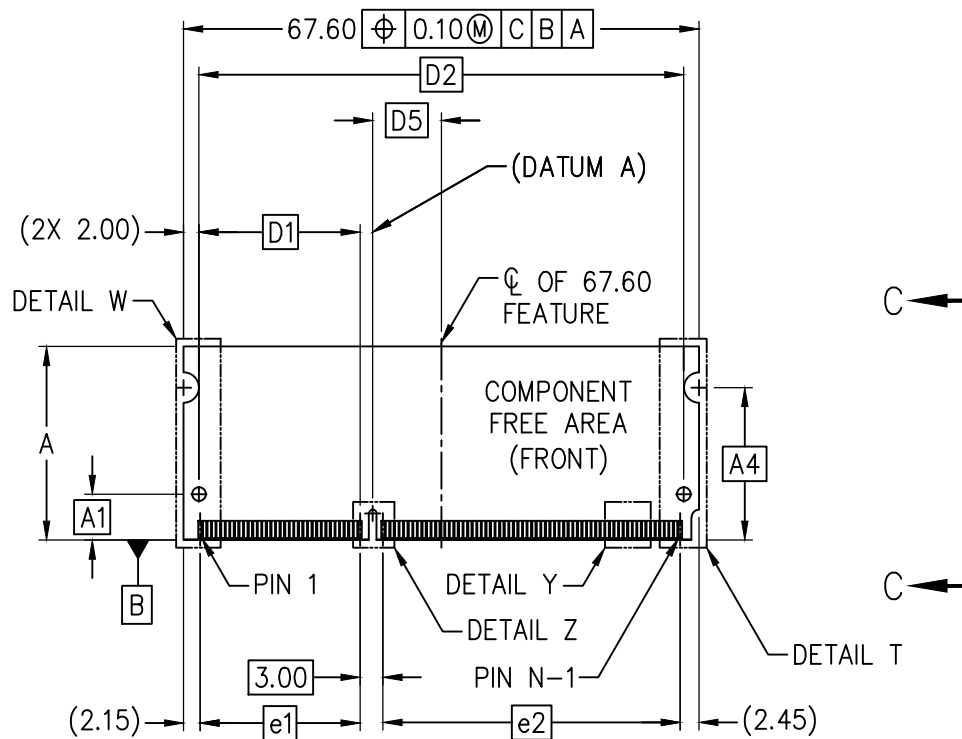




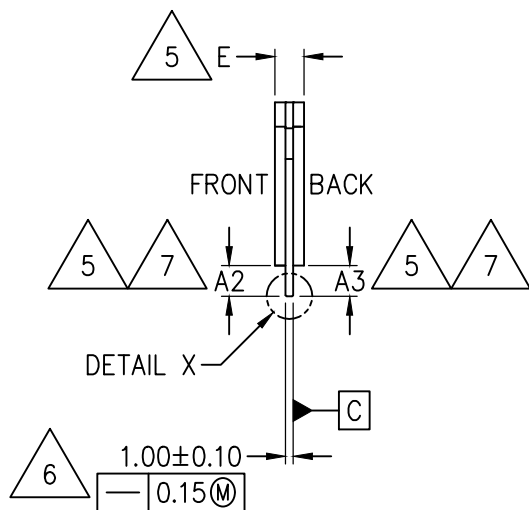
JEDEC SOLID STATE PRODUCT OUTLINE Copyright © 2014 JEDEC		THIS <i>REGISTERED OUTLINE</i> HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.				
TITLE 204 PIN DDR3 SODIMM, 0.60 MM PITCH		PACKAGE DESIGNATOR DIM	NUMBER MO-268	ISSUE E-1	DATE MAR 2014	SHEET 1 OF 20



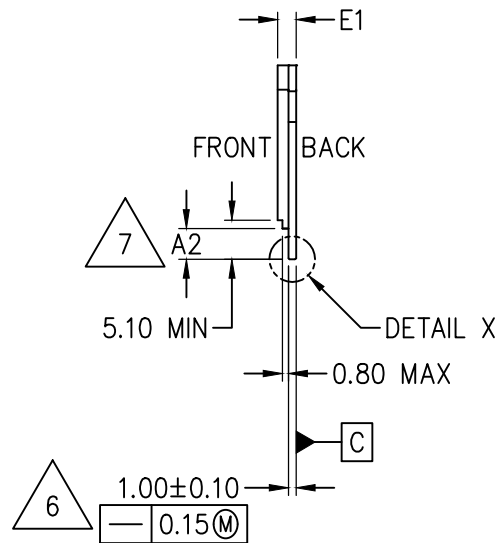
STANDARD SINGLE SIDED MODULE



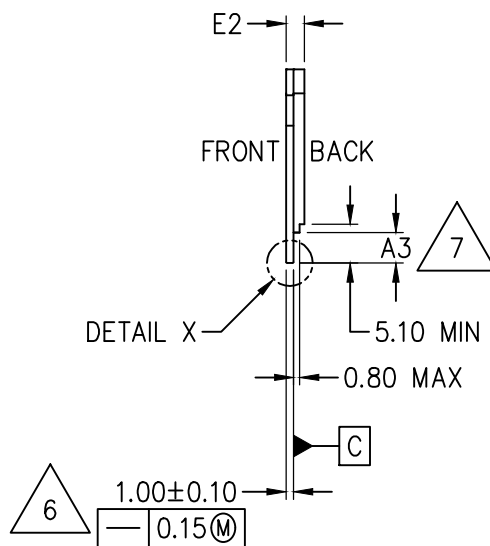
REVERSE SINGLE SIDED MODULE



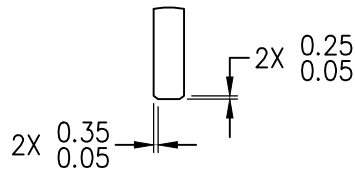
VIEW A-A



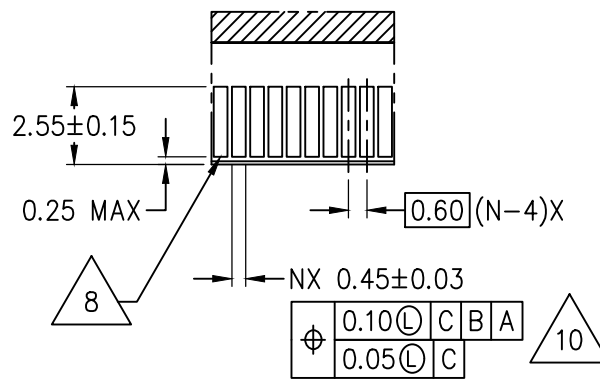
VIEW B-B



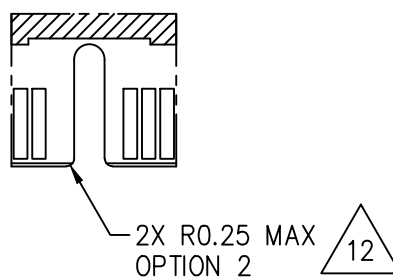
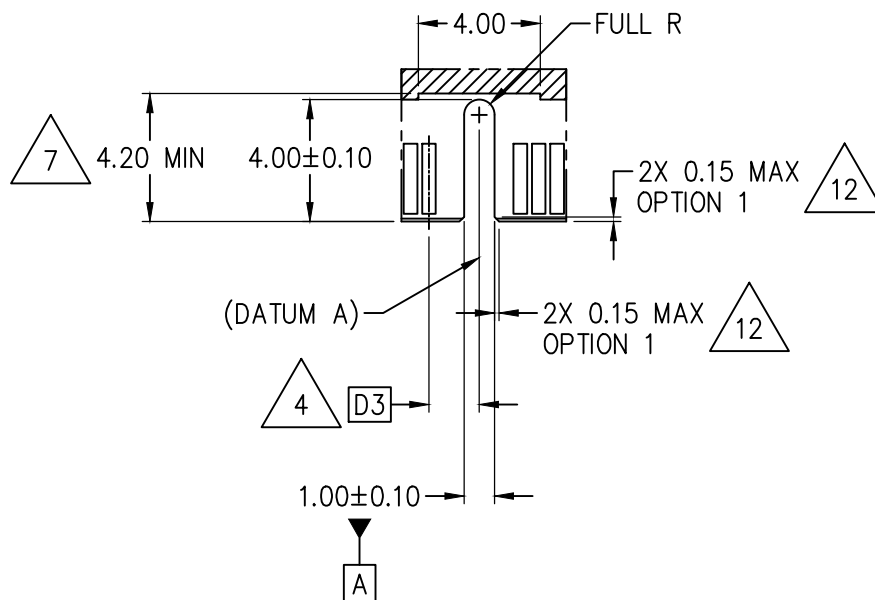
VIEW C-C



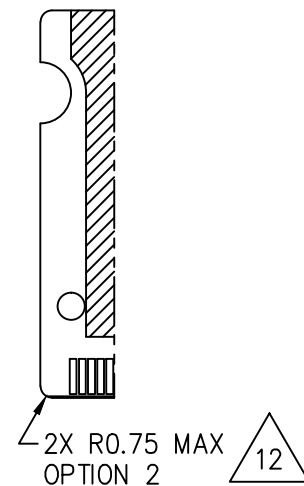
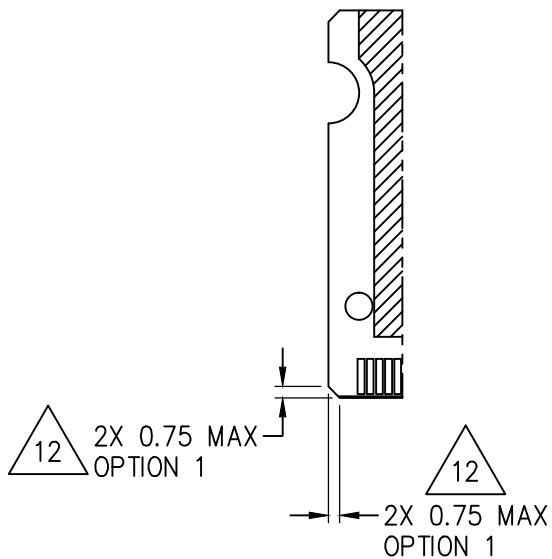
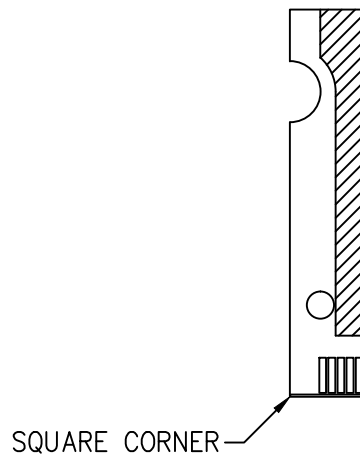
DETAIL X
(OPTIONAL)



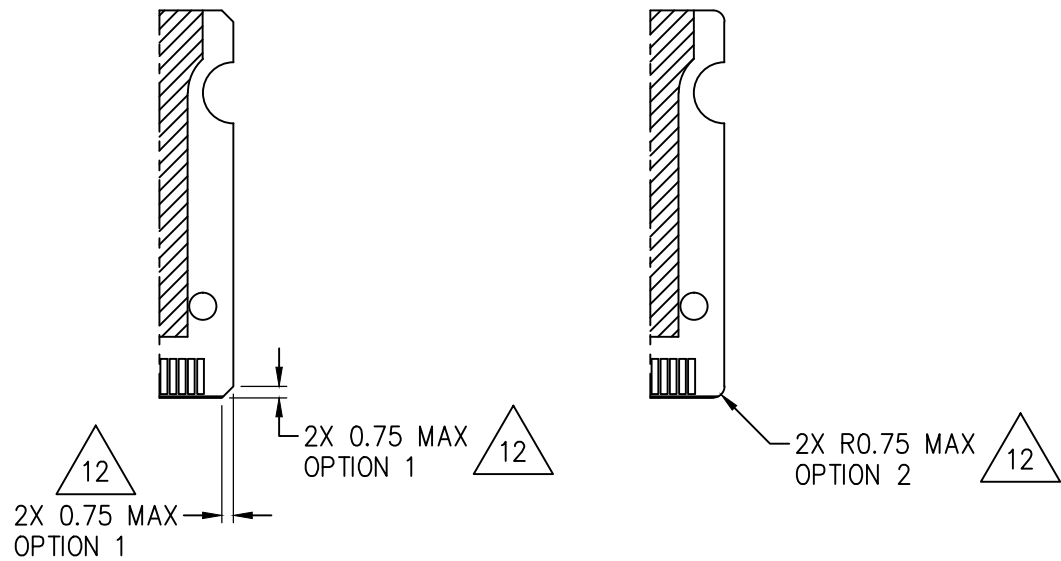
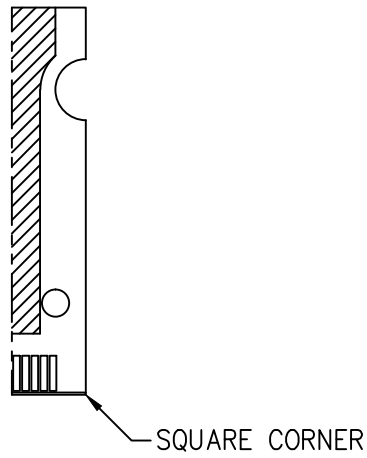
DETAIL Y



DETAIL Z



DETAIL W
SHOWN WITH COMPONENT AREA BUT CAN BE WITHOUT
COMPONENT AREA DEPENDING ON MODULE CONFIGURATION



DETAIL V